1. A lead-free solder consisting essentially of:

at least one selected from the group consisting of 0.01 to 1% by weight of Co, 0.01 to 0.2% by weight of Fe, 0.01 to 0.2% by weight of Mn, 0.01 to 0.2% by weight of Cr, and 0.01 to 2% by weight of Pd;

0.5 to 2% by weight of Cu; and

90.5% by weight or more of Sn.

2. A soldered article comprising an article containing a transition metal conductor and being joined through a solder, said transition metal conductor being liable to spread in molten Sn, wherein said solder is a lead free solder according to claim 1.

3. A soldered article according to claim 2, wherein said transition metal conductor comprises at least one selected from elementary substances or alloys thereof of the group consisting of Cu, Ag, Ni, Au, Pd, Pt and Zn.

4. A lead-free solder according to claim 1, consisting essentially of:

at least one selected from the group consisting of 0.4 to 0.5% by weight of Co, 0.05 to 0.1% by weight of Fe, 0.05 to 0.1% by weight of Mn, 0.05 to 0.1% by weight of Cr, and 0.4 to 0.6% by weight of Pd;

0.5 to 1% by weight of Cu; and

90.5% by weight or more of Sn.

5. A lead-free solder according to claim 4 containing only one member of said group.

6. A lead-free solder according to claim 1 containing only one member of said group.